

### CMD90N04-VB Datasheet

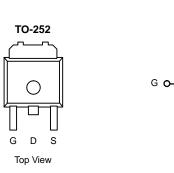
## N-Channel 40-V (D-S) MOSFET

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N-Channel MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a, c</sup>	Q <sub>g</sub> (Typ.)			
40	0.0016 at $V_{GS}$ = 10 V	120	120 nC			
40	0.0020 at V <sub>GS</sub> = 4.5 V	100	120110			
			D			



#### FEATURES

- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

#### **APPLICATIONS**

- Synchronous Rectification
- Power Supplies



Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	40	V		
Gate-Source Voltage		V <sub>GS</sub>	± 25	V	
	T <sub>C</sub> = 25 °C		120 <sup>a, c</sup>		
Continuous Droin Current $(T = 175 °C)$	T <sub>C</sub> = 70 °C		96 <sup>c</sup>		
Continuous Drain Current ( $T_J = 175 \ ^{\circ}C$ )	T <sub>A</sub> = 25 °C	I <sub>D</sub>	29 <sup>b</sup>	A	
	T <sub>A</sub> = 70 °C		23 <sup>b</sup>	A	
Pulsed Drain Current		I <sub>DM</sub>	250		
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	96		
Single Pulse Avalanche Energy	L = 0.1 MH	E <sub>AS</sub>	320	mJ	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		120 <sup>a, c</sup>	А	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.6 <sup>b</sup>	A	
	T <sub>C</sub> = 25 °C		312 <sup>a</sup>		
Maximum David Dissingtion	T <sub>C</sub> = 70 °C		200	14/	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.13 <sup>b</sup>	— W	
	T <sub>A</sub> = 70 °C		2.0 <sup>b</sup>	1	
Operating Junction and Storage Temperature R	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.33	0.4	°C/VV		

Notes:

a. Based on  $T_C = 25$  °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 120 A.

<b>SPECIFICATIONS</b> $T_J = 25$ °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	40			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		41		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <u>0</u> – 200 µ/ (		- 8		11107 C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.2		2.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 V, V_{GS} = 0 V$			1	μA	
Zelo Gale voltage Drain Guirent	'DSS	$V_{DS}$ = 40 V, $V_{GS}$ = 0 V, $T_{J}$ = 55 °C			10	μΛ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5$ V, $V_{GS} = 10$ V	120			А	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$		0.0016		Ω	
Diam-Source On-State Resistance	TOS(on)	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		0.0020		52	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 30 \text{ A}$		180		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			9000			
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = 20 V, $V_{GS}$ = 0 V, f = 1 MHz		650		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			450			
Total Gate Charge	Qg			120	180	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = 20 V, $V_{GS}$ = 10 V, $I_D$ = 20 A		30			
Gate-Drain Charge	Q <sub>gd</sub>			16			
Gate Resistance	Rg	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			20	30		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 20 V, $R_L$ = 1.0 $\Omega$		11	17		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ 20 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		77	115		
Fall Time	t <sub>f</sub>			10	15	nc	
Turn-On Delay Time	t <sub>d(on)</sub>			102	155	ns	
Rise Time	t <sub>r</sub>	$V_{DD}$ = 20 V, $R_L$ = 1.0 $\Omega$		62	95		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20$ A, $V_{GEN}$ = 4.5 V, $R_g$ = 1 $\Omega$		180	270		
Fall Time	t <sub>f</sub>			60	90		
Drain-Source Body Diode Characteristics	6						
Continuous Source-Drain Diode Current	ا <sub>S</sub>	$T_{\rm C} = 25 \ ^{\circ}{\rm C}$			110	A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				200	~	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			50	75	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs, T <sub>.I</sub> = 25 °C		70	105	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$r_{\rm F} = 20$ A, $a_{\rm F}a_{\rm F} = 100$ A/ $\mu$ s, $r_{\rm J} = 20$ C		30			
Reverse Recovery Rise Time	t <sub>b</sub>			20		ns	

Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

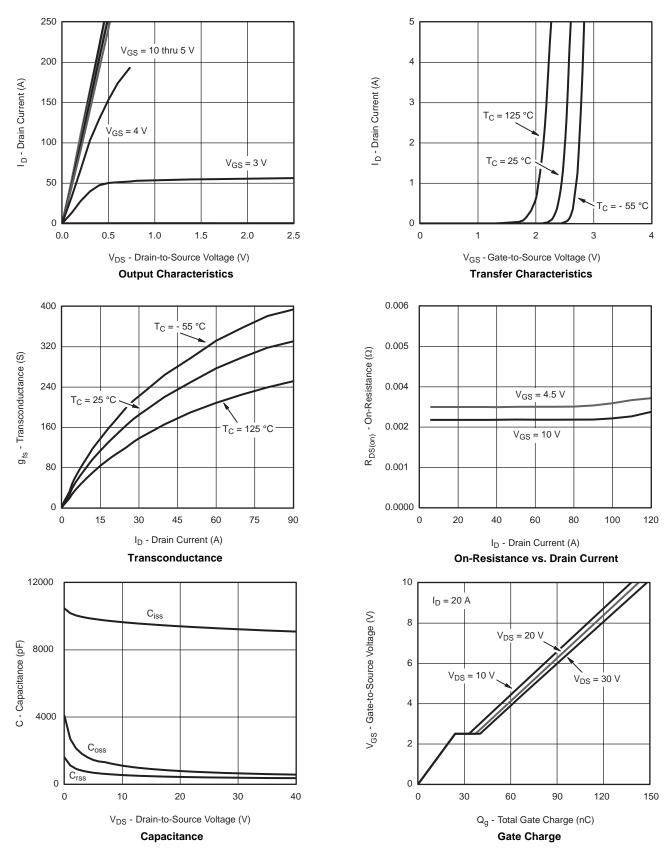
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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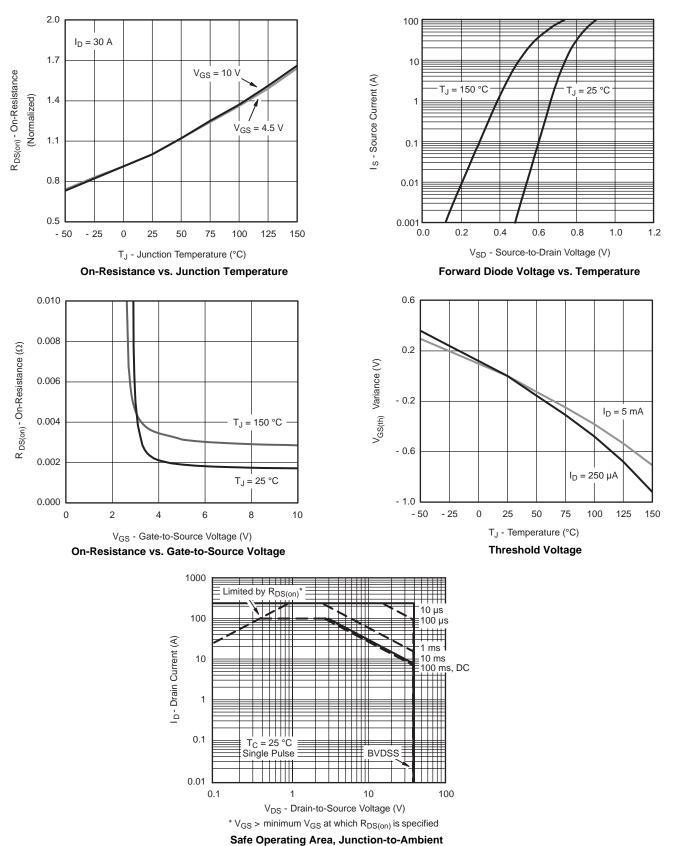


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

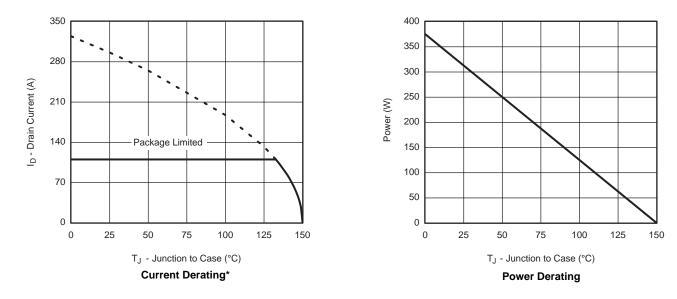




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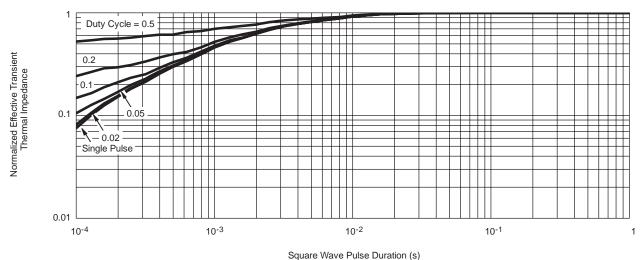






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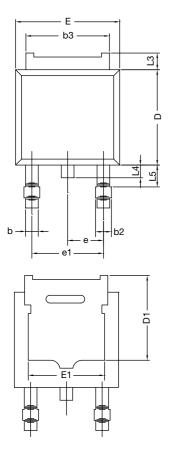
\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

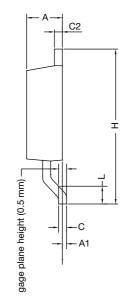


Normalized Thermal Transient Impedance, Junction-to-Case



## **TO-252AA CASE OUTLINE**





	MILLIMETERS		INC	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28	BSC	0.090	BSC		
e1	4.56	BSC	0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347						

Note

• Dimension L3 is for reference only.



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